

LNJ326W83RA

Ultra High Bright Surface Mounting Chip LED

InGaAlP UTSS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	40	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, pulse width 10 ms.

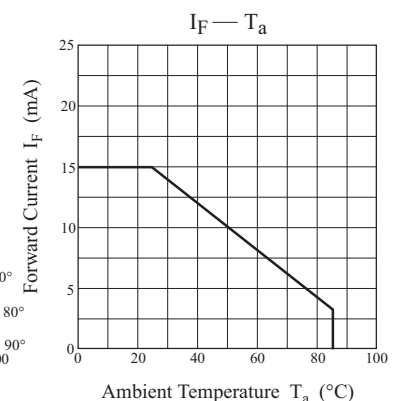
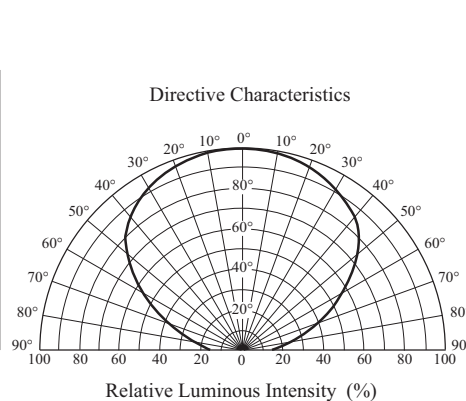
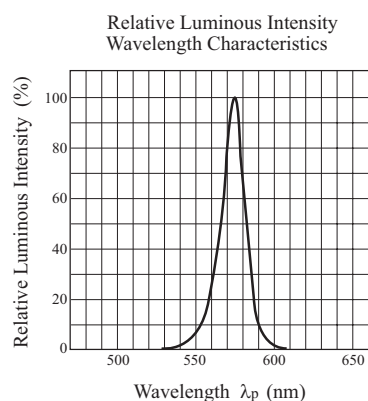
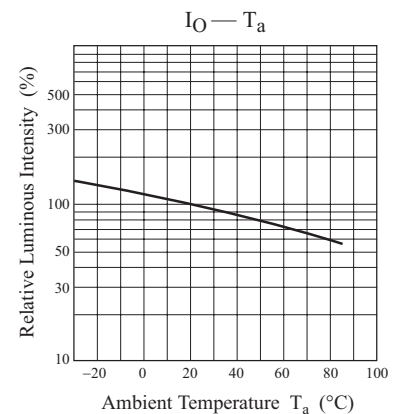
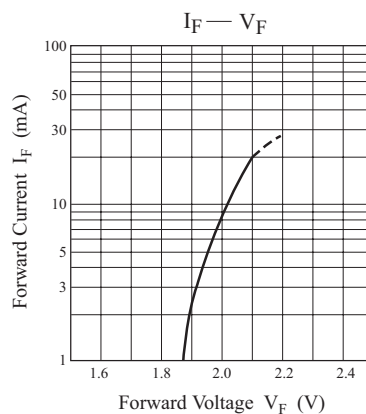
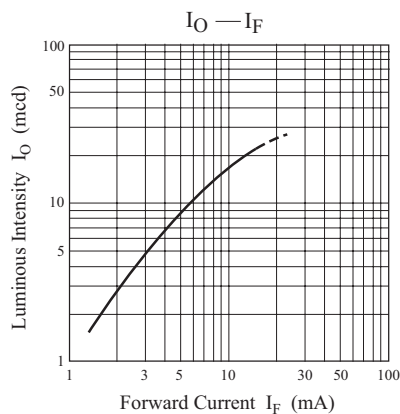
■ Lighting Color

- Green

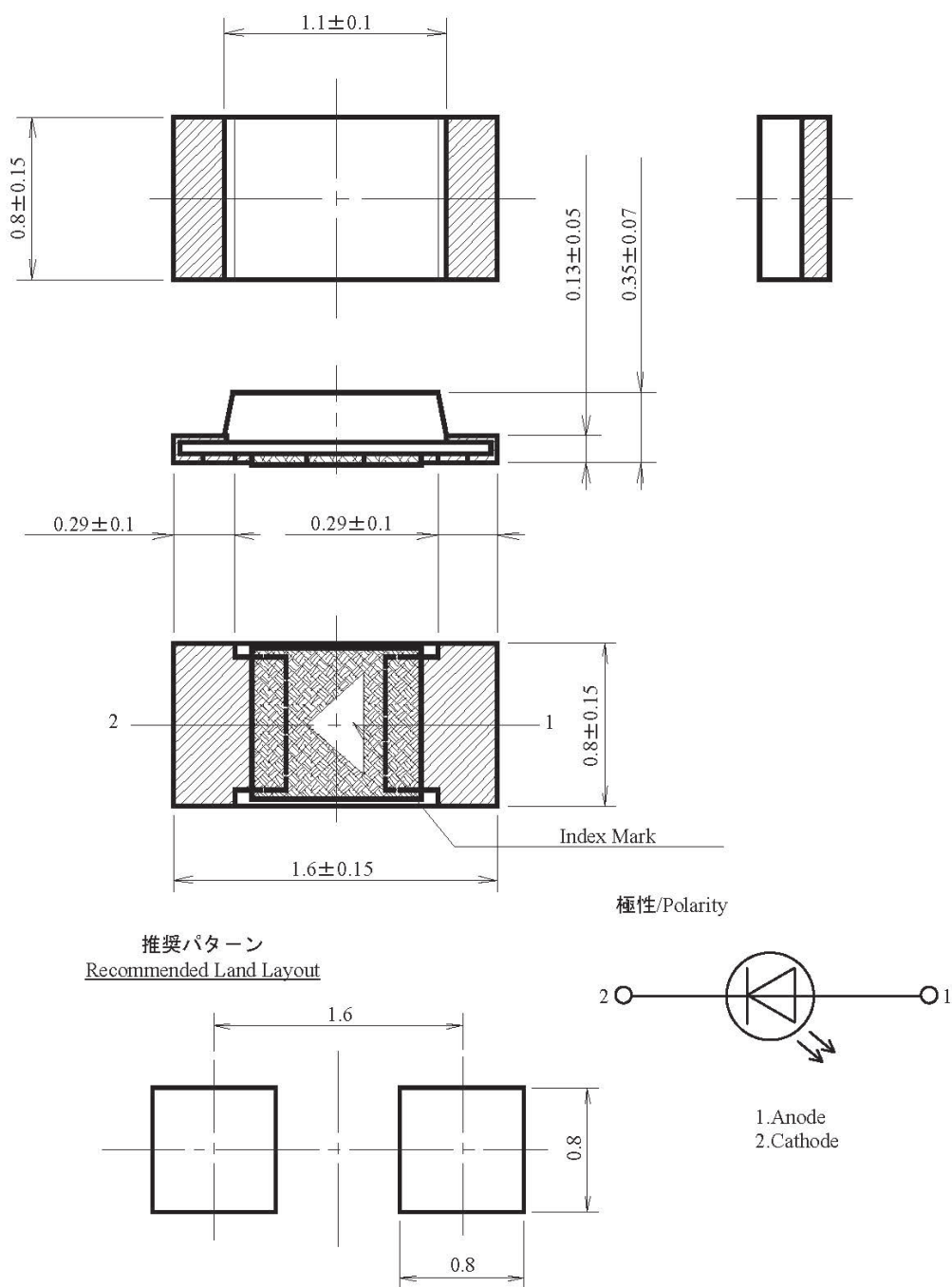
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	14	18	50	mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.05	2.5	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		575		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm
Dominant emission wavelength	λ_d	$I_F = 10\text{ mA}$	567	572	575	nm

Note) Be careful of the product destruction by static electricity.



■ Package (Unit: mm)



注記/Notes

1. パッケージ寸法については電極バリを含まない。
Measurement of the package doesn't include electrode projection.
2. 単位:mm/Unit : mm

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